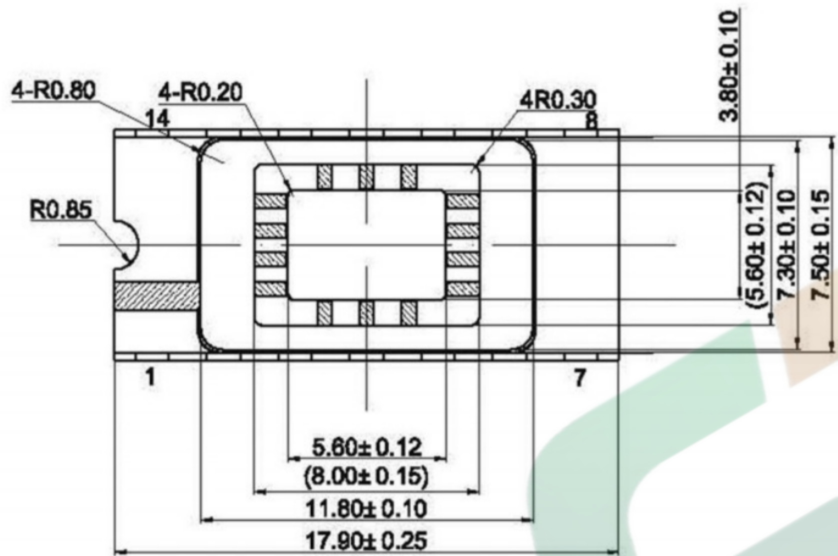

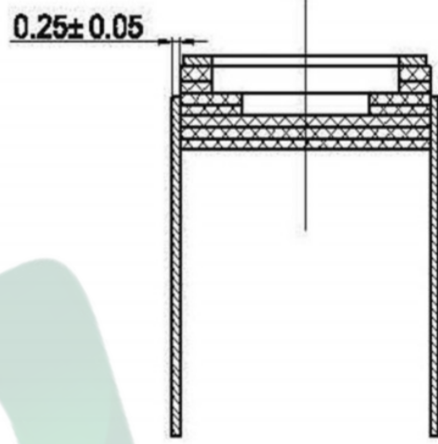

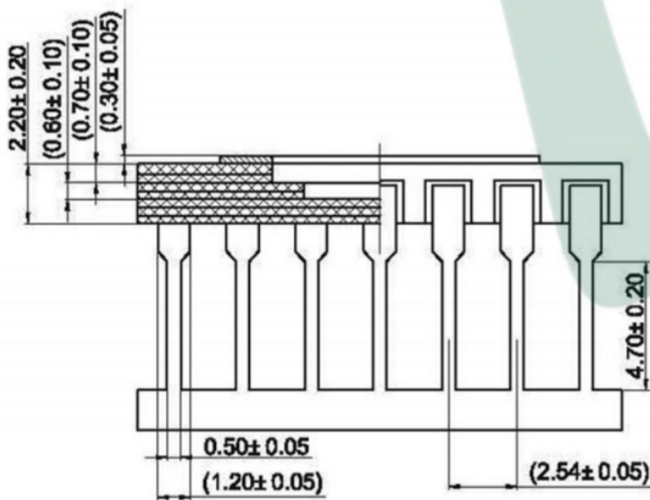

NOTES:

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. LEAD RESISTANCE : 0.2 OHM MAX.
3. SEAL AREA TO BE METALLIZED.
4. DIE ATTACH AREA TO BE METALLIZED.
5. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
6. (C) WIRE BOND PAD CONNECTED TO CORRESPONDED OUTER LEADS.
7. (C) MISALIGNMENT OF METALLIZATION PATTERN IN CAVITY SHALL BE ACCEPTED DUE TO LAYER MISALIGNMENT.

上海季丰电子科技有限公司
GIGA FORCE ELECTRONICS CO.,Limited

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